

**LTM2881 32LD 15mm X 11.25mm X 2.82mm (TABLE OF MATERIAL DECLARATION)**

*The LTM2881 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

| No.                  | Part Name                 | Material Name | Component Weight (gram) | Materials Analysis (element)                                       | CAS Number            | Material Mass (gram) | Materials Analysis (weight %) |
|----------------------|---------------------------|---------------|-------------------------|--|-----------------------|----------------------|-------------------------------|
| 1                    | Substrate                 | Circuit Board | 0.1592                  | Barium Compounds   | 7727-43-7             | 0.00252              | 1.5800                        |
|                      |                           |               |                         | Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline) | 13776-74-4, 7631-86-9 | 0.04146              | 26.0400                       |
|                      |                           |               |                         | Copper Metal   | 7440-50-8             | 0.07459              | 46.8500                       |
|                      |                           |               |                         | Copper Compounds   | 1328-53-6             | 0.00002              | 0.0140                        |
|                      |                           |               |                         | Ecotoxic substances  | 7440-38-2, 7440-28-0  | 0.00001              | 0.0050                        |
|                      |                           |               |                         | Gold metal or alloy  | 7440-57-5             | 0.00032              | 0.2000                        |
|                      |                           |               |                         | Nickel   | 7440-02-0             | 0.00204              | 1.2800                        |
|                      |                           |               |                         | Zinc   | 7440-66-6             | 0.00008              | 0.0510                        |
|                      |                           |               |                         | Continuous Filament Fiber Glass                                    | -                     | 0.03257              | 20.4600                       |
|                      |                           |               |                         | Acrylic Resin  | -                     | 0.00479              | 3.0100                        |
|                      |                           |               |                         | Epoxy Resin  | -                     | 0.00005              | 0.0340                        |
|                      |                           |               |                         | Chromium(III) Oxide  | 1308-38-9             | 0.00000              | 0.0020                        |
|                      |                           |               |                         | Silica amorphous   | 7631-86-9             | 0.00003              | 0.0190                        |
|                      |                           |               |                         | Talc;not containing fibers like asbestos                           | 14807-96-9            | 0.00029              | 0.1800                        |
|                      |                           |               |                         | Aromatic Carbonyl compounds  | -                     | 0.00027              | 0.1700                        |
|                      |                           |               |                         | Cyanoguanidine   | 461-58-5              | 0.00001              | 0.0050                        |
|                      |                           |               |                         | Imidazole system curing reagent                                    | -                     | 0.00000              | 0.0030                        |
|                      |                           |               |                         | Amine compounds  | -                     | 0.00004              | 0.0220                        |
|                      |                           |               |                         | Leveling agent and others  | -                     | 0.00011              | 0.0690                        |
| 2                    | Solder Paste              | Alloy         | 0.0064                  | Sn   | 7440-31-5             | 0.00606              | 95.0000                       |
|                      |                           |               |                         | Sb   | 7440-36-0             | 0.00032              | 5.0000                        |
| 3                    | Epoxy                     |               | 0.0056                  | Di-ester resin   | -                     | 0.00045              | 8.0000                        |
|                      |                           |               |                         | Functionalized ester   | -                     | 0.00045              | 8.0000                        |
|                      |                           |               |                         | Silver   | 7440-22-4             | 0.00469              | 84.0000                       |
| 4                    | Passive/Active Components |               | 0.1936                  | Capacitor  | -                     | 0.07363              | 38.0379                       |
|                      |                           |               |                         | Transformer  | -                     | 0.11994              | 61.9621                       |
| 5                    | Active Ics                | Silicon       | 0.0046                  | Silicon  | 7440-21-3             | 0.00456              | 100.0000                      |
| 6                    | Wire                      | Gold          | 0.0012                  | Au   | 7440-57-5             | 0.00118              | 99.9900                       |
| 7                    | Encapsulation             | Epoxy Resin   | 0.6855                  | Fused Silica   | 60676-86-0            | 0.52917              | 77.2000                       |
|                      |                           |               |                         | Epoxy Resin  | -                     | 0.06101              | 8.9000                        |
|                      |                           |               |                         | Phenol Resin   | -                     | 0.06101              | 8.9000                        |
|                      |                           |               |                         | Crytalline Silica  | 14808-60-7            | 0.02056              | 3.0000                        |
|                      |                           |               |                         | Carbon Black   | 1333-86-4             | 0.00343              | 0.5000                        |
|                      |                           |               |                         | Metal Hydroxide  | -                     | 0.01028              | 1.5000                        |
| Total Package Weight |                           |               | 1.0560                  |  |                       |                      |                               |

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts